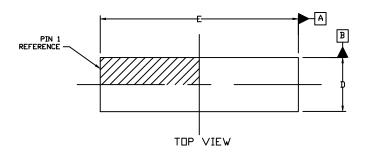
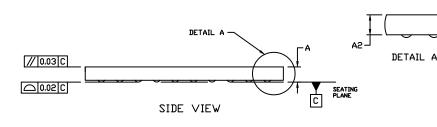
## WLCSP30, 1.175x4.3x0.33 CASE 567WW ISSUE O

**DATE 18 JUL 2018** 

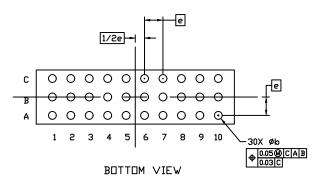


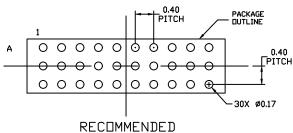
## NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPERICAL CROWNS OF THE CONTACT BALLS.
- 4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE CONTACT BALLS.
- 5. DIMENSION 6 IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.



	MILLIMETERS		
DIM	MIN.	N□M.	MAX.
Α	0.31	0.33	0.35
A1	0.034	0.040	0.046
A2	0.278	0.290	0.303
b	0.15	0.17	0.19
D	1.15	1.175	1.20
E	4.275	4.30	4.325
е	0.40 BSC		





MOUNTING FOOTPRINT

## GENERIC MARKING DIAGRAM\*

° XXXXXXXX AWLYYWW

XXXX = Specific Device Code

A = Assembly Location

WL = Wafer Lot YY = Year

WW = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot " •", may or may not be present. Some products may not follow the Generic Marking.

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